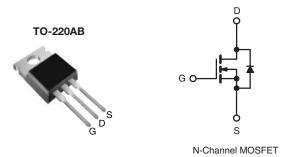


Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	600				
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V 1.2				
Q _g (Max.) (nC)	42				
Q _{gs} (nC)	10				
Q _{gd} (nC)	20				
Configuration	Single				



FEATURES

• Low Gate Charge Qq Results in Simple Drive



 Improved Gate, Avalanche and Dynamic dV/dt RoHS Ruggedness

- Fully Characterized Capacitance and Avalanche Voltage and Current
- Effective Coss Specified
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply
- High Speed Power Switching

TYPICAL SMPS TOPOLOGIES

• Single Transistor Forward

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRFBC40APbF
	SiHFBC40A-E3
SnPb	IRFBC40A
	SiHFBC40A

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	600	V	
Gate-Source Voltage			V _{GS}	± 30		
Continuous Duois Current	V -140V	T _C = 25 °C		6.2		
Continuous Drain Current	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	I _D	3.9	А	
Pulsed Drain Current ^a			I _{DM}	25		
Linear Derating Factor				1.0	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	570	mJ	
Repetitive Avalanche Currenta			I _{AR}	6.2	Α	
Repetitive Avalanche Energy ^a			E _{AR}	13	mJ	
Maximum Power Dissipation $T_C = 25 ^{\circ}C$			P _D	125	W	
Peak Diode Recovery dV/dt ^c			dV/dt	6.0	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 150	20	
Soldering Recommendations (Peak Temperature) for 10 s				300 ^d	°C	
Manustina Tanana	6-32 or M3 screw			10	lbf ⋅ in	
Mounting Torque				1.1	N · m	

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Starting T_J = 25 °C, L = 29.6 mH, R_q = 25 Ω , I_{AS} = 6.2 A (see fig. 12).
- c. $I_{SD} \le 6.2$ A, $dI/dt \le 80$ A/ μ s, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C.
- d. 1.6 mm from case.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply

IRFBC40A, SiHFBC40A

Vishay Siliconix



THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum Junction-to-Ambient	R _{thJA}	-	62			
Case-to-Sink, Flat, Greased Surface	R _{thCS}	0.50	-	°C/W		
Maximum Junction-to-Case (Drain)	R _{thJC}	=	1.0			

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, I _D = 1 mA		0.66	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	V _{DS} :	= V _{GS} , I _D = 250 μA	2.0	-	4.0	٧
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 30 V		-	± 100	nA
Zoro Coto Voltago Droin Current		V _{DS} =	V _{DS} = 600 V, V _{GS} = 0 V		-	25	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	250	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 3.7 A ^b	-	-	1.2	Ω
Forward Transconductance	9 _{fs}	V _{DS}	= 50 V, I _D = 3.7 A	3.4	-	-	S
Dynamic							
Input Capacitance	C _{iss}		$V_{GS} = 0 V$,	-	1036	-	
Output Capacitance	Coss		$V_{DS} = 25 \text{ V},$	-	136	-	
Reverse Transfer Capacitance	C _{rss}	f = 1.0 MHz, see fig. 5		-	7.0	-	1
Output Capacitance	C _{oss}	V _{GS} = 0 V	V _{DS} = 1.0 V, f = 1.0 MHz	-	1487	-	- pF -
			V _{DS} = 480 V, f = 1.0 MHz	-	36	-	
Effective Output Capacitance	C _{oss} eff.		V _{DS} = 0 V to 480 V ^c	-	48	-	
Total Gate Charge	Qg			-	-	42	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 6.2 \text{ A}, V_{DS} = 480 \text{ V}$ see fig. 6 and 13 ^b		-	10	nC
Gate-Drain Charge	Q _{gd}		See fig. 6 and 16	-	-	20	1
Turn-On Delay Time	t _{d(on)}			-	13	-	
Rise Time	t _r		V _{DD} = 300 V, I _D = 6.2 A		23	-	
Turn-Off Delay Time	t _{d(off)}	$R_g = 9.1 \ \Omega, R_D = 47 \ \Omega,$ see fig. 10^b		-	31	-	ns
Fall Time	t _f			-	18	-	
Drain-Source Body Diode Characteristic	s	-					
Continuous Source-Drain Diode Current	Is	MOSFET symbol showing the integral reverse p - n junction diode		ı	-	6.2	^
Pulsed Diode Forward Current ^a	I _{SM}			-	-	25	Α
Body Diode Voltage	V_{SD}	$T_J = 25$ °C, $I_S = 6.2$ A, $V_{GS} = 0$ V ^b		-	-	1.5	V
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = 6.2 A, dI/dt = 100 A/μs ^b		-	431	647	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	1.8	2.8	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)				[P)	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width $\leq 300~\mu s;$ duty cycle $\leq 2~\%.$
- c. C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80 % V_{DS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

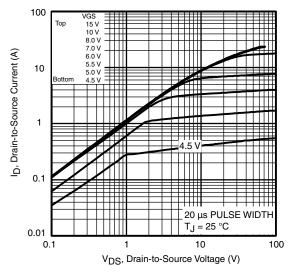


Fig. 1 - Typical Output Characteristics

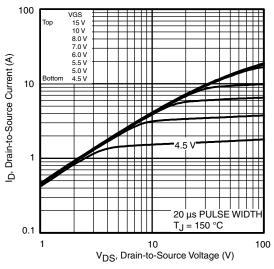


Fig. 2 - Typical Output Characteristics

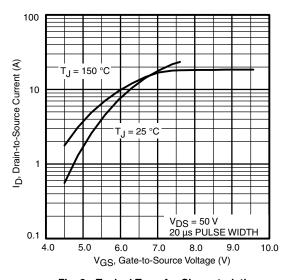


Fig. 3 - Typical Transfer Characteristics

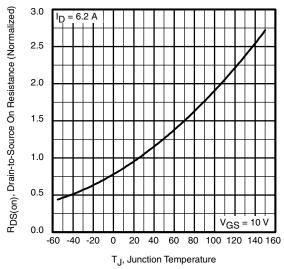


Fig. 4 - Normalized On-Resistance vs. Temperature



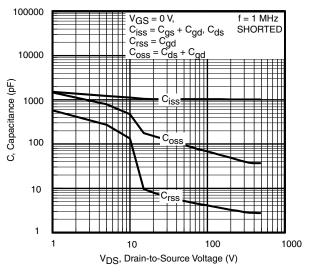


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

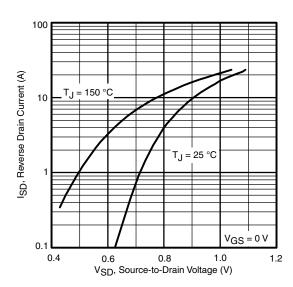


Fig. 7 - Typical Source-Drain Diode Forward Voltage

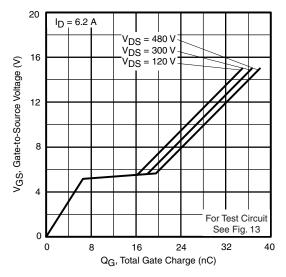


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

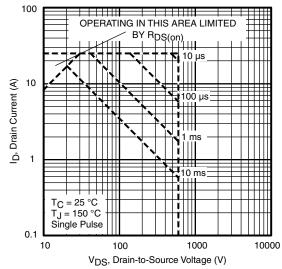


Fig. 8 - Maximum Safe Operating Area



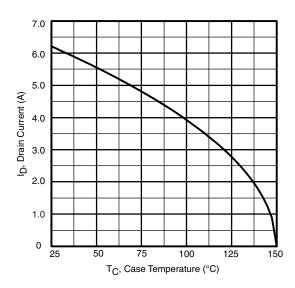


Fig. 9 - Maximum Drain Current vs. Case Temperature

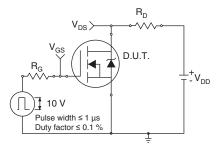


Fig. 10a - Switching Time Test Circuit

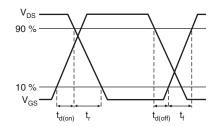


Fig. 10b - Switching Time Waveforms

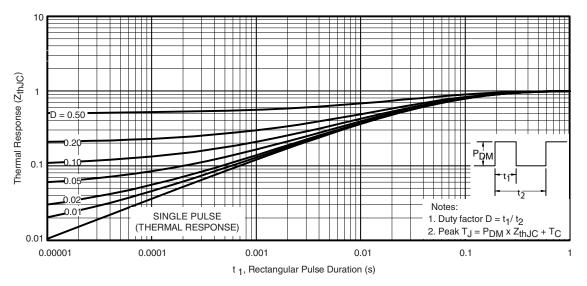


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



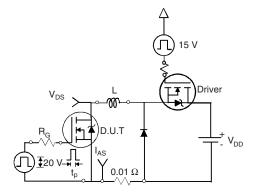


Fig. 12a - Unclamped Inductive Test Circuit

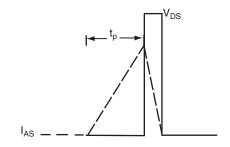


Fig. 12b - Unclamped Inductive Waveforms

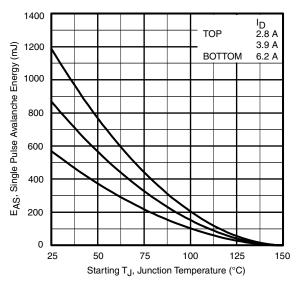


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

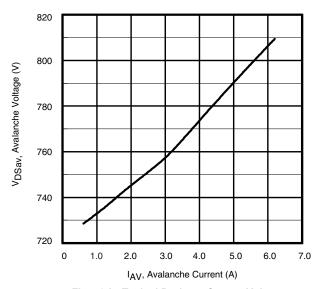


Fig. 12d - Typical Drain-to-Source Voltage vs.
Avalanche Current

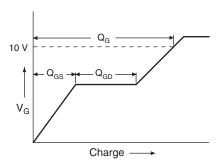


Fig. 13a - Basic Gate Charge Waveform

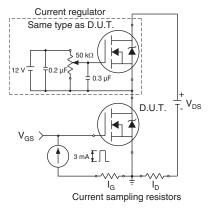
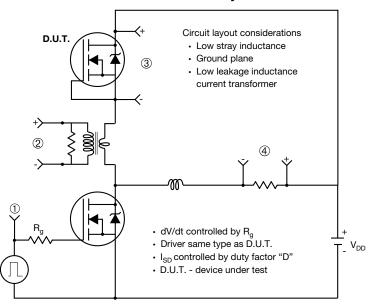


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



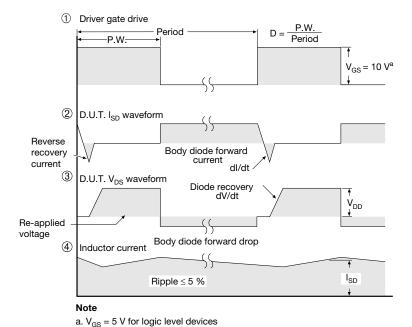


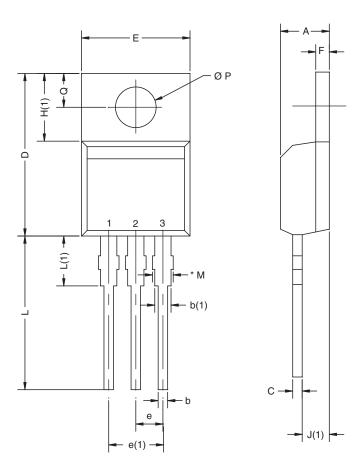
Fig. 14 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?91112.





TO-220AB



	MILLIN	METERS	INC	HES		
DIM.	MIN.	MAX.	MIN.	MAX.		
Α	4.25	4.65	0.167	0.183		
b	0.69	1.01	0.027	0.040		
b(1)	1.20	1.73	0.047	0.068		
С	0.36	0.61	0.014	0.024		
D	14.85	15.49	0.585	0.610		
Е	10.04	10.51	0.395	0.414		
е	2.41	2.67	0.095	0.105		
e(1)	4.88	5.28	0.192	0.208		
F	1.14	1.40	0.045	0.055		
H(1)	6.09	6.48	0.240	0.255		
J(1)	2.41	2.92	0.095	0.115		
L	13.35	14.02	0.526	0.552		
L(1)	3.32	3.82	0.131	0.150		
ØΡ	3.54	3.94	0.139	0.155		
Q	2.60	3.00	0.102	0.118		
ECN: X10-0416-Rev. M, 01-Nov-10						

DWG: 5471

 $^{^{\}star}$ M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM





Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk and agree to fully indemnify and hold Vishay and its distributors harmless from and against any and all claims, liabilities, expenses and damages arising or resulting in connection with such use or sale, including attorneys fees, even if such claim alleges that Vishay or its distributor was negligent regarding the design or manufacture of the part. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

Document Number: 91000 www.vishay.com Revision: 11-Mar-11